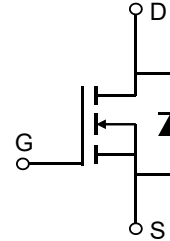


Description

Features

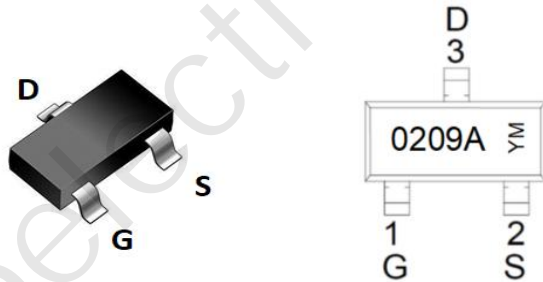
- 20V, 9A
- $R_{DS(ON)}$ Typ = 10.3mΩ @ $V_{GS} = 4.5V$
- $R_{DS(ON)}$ Typ = 12.8mΩ @ $V_{GS} = 2.5V$
- Advanced Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- Lead Free



Schematic Diagram

Application

- Load Switch
- PWM Application
- Power Management



Marking and Pin Assignment

Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMJTU0209A	0209A	SOT-23-3L	TAPING	7"	3000	120000

Absolute Maximum Ratings (@ $T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Value	Units
V_{DS}	Drain-to-Source Voltage	20	V
V_{GS}	Gate-to-Source Voltage	±12	V
I_D	Continuous Drain Current	$T_A = 25^\circ\text{C}$	9
		$T_A = 100^\circ\text{C}$	5.4
I_{DM}	Pulsed Drain Current ⁽¹⁾	36	A
P_D	Power Dissipation	$T_A = 25^\circ\text{C}$	1.73
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient ⁽²⁾	72	°C/W
T_J, T_{STG}	Junction & Storage Temperature Range	-55 to 150	°C

Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	I _D = 250μA, V _{GS} = 0V	20	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 20V, V _{GS} = 0V	-	-	1.0	μA
I _{GSS}	Gate-Body Leakage Current	V _{DS} = 0V, V _{GS} = ±12V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	0.5	0.7	1.0	V
R _{DS(ON)}	Static Drain-Source ON-Resistance ⁽³⁾	V _{GS} = 4.5V, I _D = 3A	-	10.3	13.3	mΩ
		V _{GS} = 2.5V, I _D = 2A	-	12.8	16.6	mΩ
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{GS} = 0V, V _{DS} = 10V, f = 1MHz	-	1140	-	pF
C _{oss}	Output Capacitance		-	160	-	pF
C _{rss}	Reverse Transfer Capacitance		-	140	-	pF
Q _g	Total Gate Charge	V _{GS} = 0 to 4.5V V _{DS} = 10V, I _D = 9A	-	13	-	nC
Q _{gs}	Gate Source Charge		-	2.5	-	nC
Q _{gd}	Gate Drain("Miller") Charge		-	3.5	-	nC
Switching Characteristics						
t _{d(on)}	Turn-On DelayTime	V _{GS} = 4.5V, V _{DD} = 10V I _D = 9A, R _{GEN} = 3Ω	-	8	-	ns
t _r	Turn-On Rise Time		-	19	-	ns
t _{d(off)}	Turn-Off DelayTime		-	30	-	ns
t _f	Turn-Off Fall Time		-	11	-	ns
Drain-Source Diode Characteristics and Max Ratings						
I _S	Maximum Continuous Drain to Source Diode Forward Current	V _{GS} = 0V, I _S = 3A	-	-	9	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	36	A
V _{SD}	Drain to Source Diode Forward Voltage		-	-	1.2	V
t _{rr}	Body Diode Reverse Recovery Time		-	7.5	-	ns
Q _{rr}	Body Diode Reverse Recovery Charge		-	1.5	-	nC

- Notes:
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
 2. $R_{\theta JA}$ is measured with the device mounted on a 1inch² pad of 2oz copper FR4 PCB
 3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$.

Test Circuit

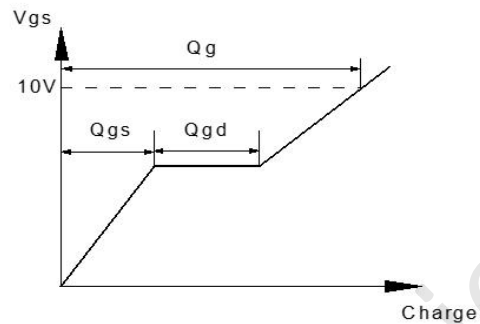
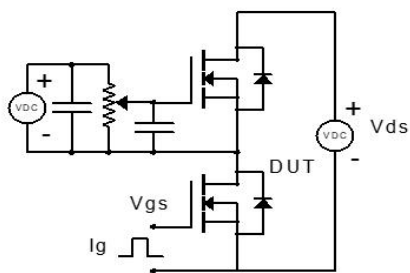


Figure 1: Gate Charge Test Circuit & Waveform

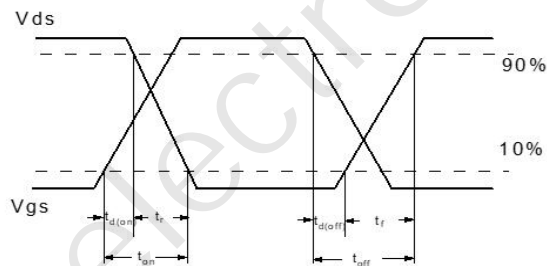
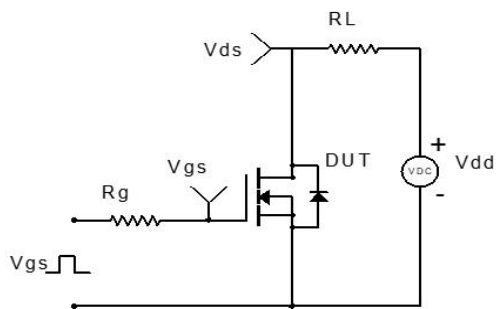


Figure 2: Resistive Switching Test Circuit & Waveform

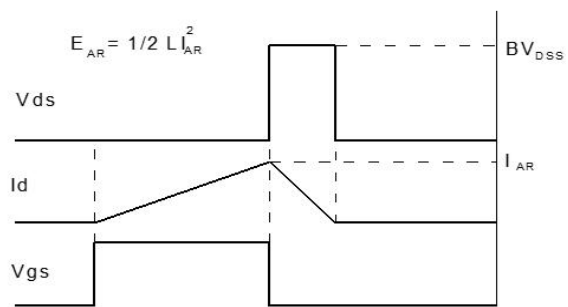
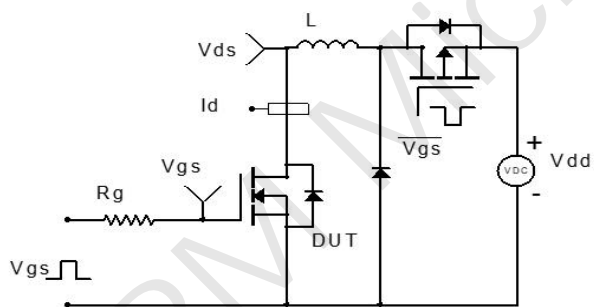


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

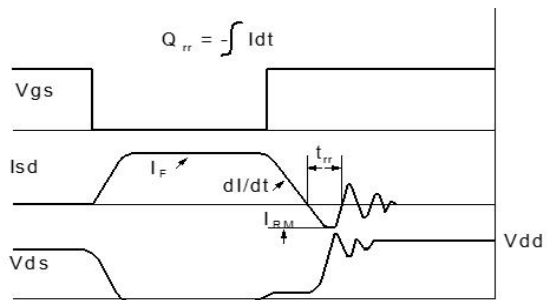
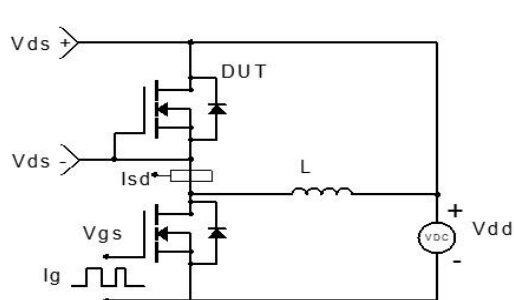
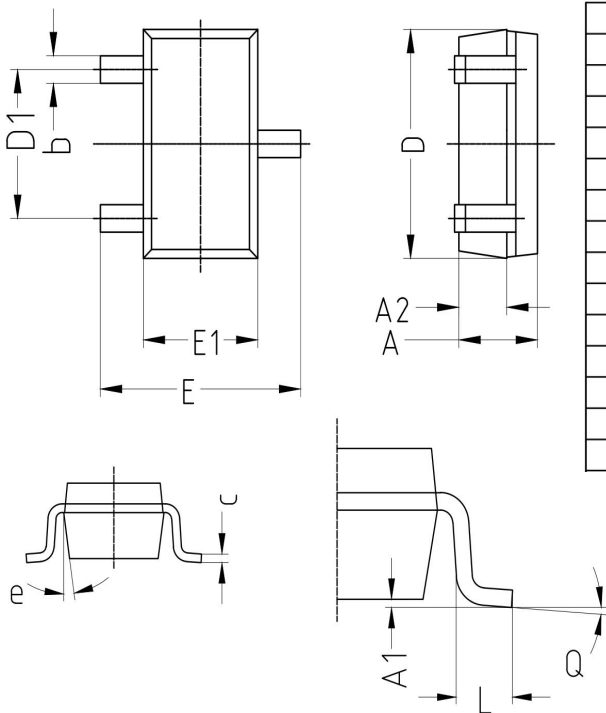


Figure 4: Diode Recovery Test Circuit & Waveform

Package Mechanical Data(SOT-23-3L)




COMMON DIMENSION (MM)			
PKG	SOT-23-3L		
Symbol	MIN	MON	MAX
A	1.080	1.100	1.120
A1	0.010	0.060	0.150
A2	0.640	0.670	0.700
b	0.325	0.350	0.375
c	0.125	0.135	0.150
D	2.92	2.930	2.980
D1	1.875	1.900	1.925
E	2.650	2.800	2.950
E1	1.580	1.600	1.670
L	0.300	0.450	0.600
e	8°		
Q	0°	4°	8°

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